showing a defect distribution on the wafer. Numerals 1602 and 1603 designate the

defect images on the wafer, the imaging conditions and the like. Numeral 1604

designates a classification result display area, in which the classified results relative

to the applicable defect images are collected on the spot to display the results

thereof. For example, the number of occurrences and the rate of occurrence

according to the categories are calculated from the classified results shown in FIG.

11 and are displayed.

IN THE CLAIMS:

Please enter the following clarified replacement Claims 1-3.

1.(Twice amended) An inspecting system comprising: an analyzing unit, said

analyzing unit including an image detection device for producing a plurality of

images of a workpiece; storage means for storing detected images produced by said

image detection device; display means having a screen with a first area for

displaying a plurality of said detected images stored in said storage means and a

plurality of second areas for classifying said detected images according to features

of said detected images; and means for moving said plurality of detected images on

said screen from said first area to selected second areas to classify said detected

images in said second areas.

2.(Twice amended) An analyzing unit comprising: storage means for storing

a plurality of images; display means having a screen with a first area for displaying

images stored in said storage means and a plurality of second areas for classifying

said images according to features of said images; and means for moving ones of

6

said plurality of images on said screen from said first area to selected second areas to classify said plurality of images in said second areas.

3.(Twice amended) A method of manufacturing an electronic device, wherein use is made of a manufacturing apparatus for processing a workpiece to form an electronic device, an inspecting apparatus for inspecting the workpiece processed by said manufacturing apparatus, an analyzing unit including an image detection device which is capable of producing an image of said workpiece, and a storage means for storing images of workpieces detected by said image detection device, the method comprising: displaying detected images stored in said storage means on a first area of a screen, the screen having a plurality of second areas for classifying said detected images according to features of said detected images; moving ones of said detected images on said screen from said first area to selected second areas to classify said detected images in said second areas; providing information to said analyzing unit concerning images in said second areas of said screen; and controlling the production line having said manufacturing apparatus arranged thereon using information obtained from said analyzing unit.

Please enter new Claims 4-11, as follows.

4.(New) An inspecting system comprising: an analyzing unit, said analyzing unit including an image detection device to produce images of semiconductor manufacturing defects for a workpiece; a display with a sorting display area in which to display ones of said images with unclassified semiconductor manufacturing defects; and a plurality of defect-classification display areas into which each image

7

of said images may be classified according to visual manufacturing defect features contained in the image; and a user-manipulated moving unit to move a subject image from said sorting display area to a selected one of said defect-classification display areas, to classify said subject image into the selected one of said defect-classification display areas.

5.(New) An inspecting system as claimed in claim 4, wherein the user-manipulated moving unit includes a user-manipulated pointing device to point to, select and drag-and-drop said subject image from said sorting display area into the selected one of said defect-classification display areas.

6.(New) An inspecting system as claimed in claim 5, wherein said user-manipulated pointing device is a mouse.

7.(New) An inspecting system as claimed in claim 4, comprising a memory to store predetermined information for at least ones of said images including defect-classification information, and an adjuster unit to adjust said defect-classification information for said subject image to match a defect classification of the selected one of said defect-classification display areas to which said subject image is moved.

8.(New) An inspecting method, comprising: using an image detection device to produce images of semiconductor manufacturing defects for a workpiece; displaying images of unclassified semiconductor manufacturing defects within a sorting display area of a display, and displaying a plurality of defect-classification

8

display areas into which each image of said images may be classified according to visual manufacturing defect features contained in the image; and user-manipulated moving of a subject image from said sorting display area to a selected one of said defect-classification display areas, to classify said subject image into the selected one of said defect-classification display areas.

9.(New) An inspecting method as claimed in claim 8, wherein said user-manipulated moving is effected with a user-manipulated pointing device to point to, select and drag-and-drop said subject image from said sorting display area into the selected one of said defect-classification display areas.

10.(New) An inspecting method as claimed in claim 9, wherein said user-manipulated pointing device is a mouse.

11.(New) An inspecting method as claimed in claim 8, comprising storing predetermined information for at least ones of said images including defect-classification information in a memory, and adjusting said defect-classification information for said subject image to match a defect classification of the selected one of said defect-classification display areas to which said subject image is moved.

IN THE ABSTRACT:

Attached hereto on a separate page is a clean copy of the "Abstract of the Disclosure" with corrections as indicated in Appendix A-Marked Version.